

1. General description

Silicon Carbide Schottky diode in a TO252 (DPAK) plastic package, designed for high frequency switched-mode power supplies.



2. Features and benefits

- Highly stable switching performance
- High forward surge capability I_{FSM}
- Extremely fast reverse recovery time
- Superior in efficiency to Silicon Diode alternatives
- Reduced losses in associated MOSFET
- Reduced EMI
- Reduced cooling requirements
- RoHS compliant
- High junction operating temperature capability ($T_{j(max)} = 175\text{ °C}$)

3. Applications

- Power factor correction
- Telecom / Server SMPS
- UPS
- PV inverter
- PC Silverbox
- LED / OLED TV
- Motor Drives

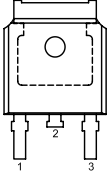
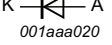
4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Values				Unit
Absolute maximum rating							
V_{RRM}	repetitive peak reverse voltage		1200				V
$I_{F(AV)}$	average forward current	$\delta = 0.5$; square-wave pulse; $T_{mb} \leq 157\text{ °C}$; Fig. 1 ; Fig. 2 ; Fig. 3	2				A
T_j	junction temperature		175				°C
Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Static characteristics							
V_F	forward voltage	$I_F = 2\text{ A}$; $T_j = 25\text{ °C}$; Fig. 5	-	1.45	1.65		V
		$I_F = 2\text{ A}$; $T_j = 150\text{ °C}$; Fig. 5	-	1.95	2.30		V
Dynamic characteristics							
Q_r	recovered charge	$I_F = 2\text{ A}$; $di_F/dt = 500\text{ A}/\mu\text{s}$; $V_R = 400\text{ V}$; $T_j = 25\text{ °C}$; Fig. 7	-	8	-		nC

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	n.c.	not connected		
2	K	cathode [1]		
3	A	anode		
mb	K	mounting base; connected to cathode		

[1] It is not possible to connect to pin 2 of the TO252 package.

6. Ordering information

Table 3. Ordering information

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
WNSC2D021200D	TO252	WNSC2D021200D6J	Reel	2500	TO252NS	14-Nov-2016

7. Marking

Table 4. Marking codes

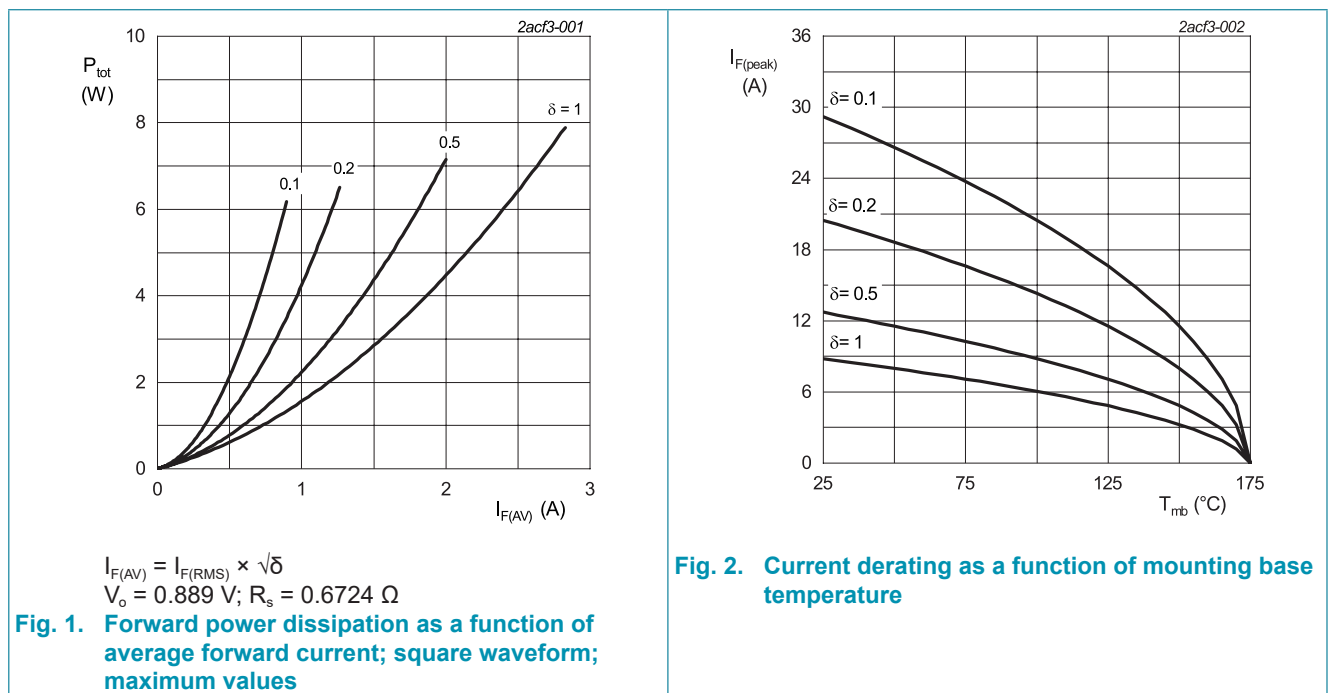
Type number	Marking codes
WNSC2D021200D	WNSC2D 02120D

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
V_{RRM}	repetitive peak reverse voltage		1200	V
V_{RWM}	crest working reverse voltage		1200	V
V_R	reverse voltage	DC	1200	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$; square-wave pulse; $T_{mb} \leq 157\text{ }^\circ\text{C}$; Fig. 1 ; Fig. 2 ; Fig. 3	2	A
I_{FRM}	repetitive peak forward current	$\delta = 0.5$; $t_p = 25\text{ }\mu\text{s}$; $T_{mb} \leq 157\text{ }^\circ\text{C}$; square-wave pulse	4	A
I_{FSM}	non-repetitive peak forward current	$t_p = 10\text{ ms}$; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$; sine-wave pulse	20	A
		$t_p = 10\text{ }\mu\text{s}$; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$; square-wave pulse	200	A
I^2t	I^2t for fusing	sine-wave pulse; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$; $t_p = 10\text{ ms}$	2	A^2s
T_{stg}	storage temperature		-55 to 175	$^\circ\text{C}$
T_j	junction temperature		175	$^\circ\text{C}$



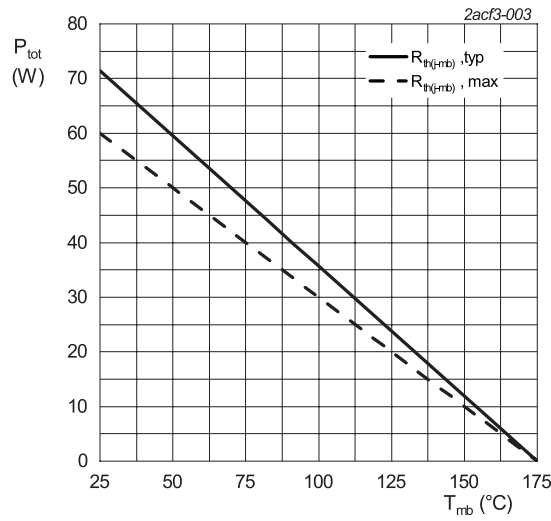


Fig. 3. Total power dissipation as a function of mounting base temperature

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	with heatsink compound; Fig. 4		-	2.1	2.5	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air		-	50	-	K/W

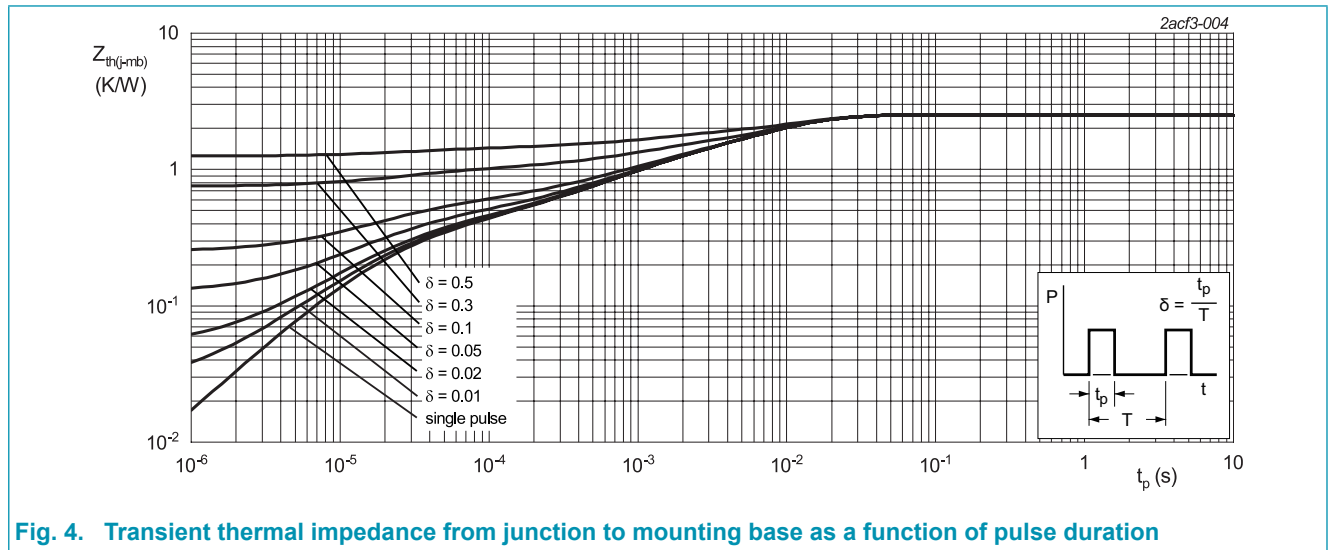
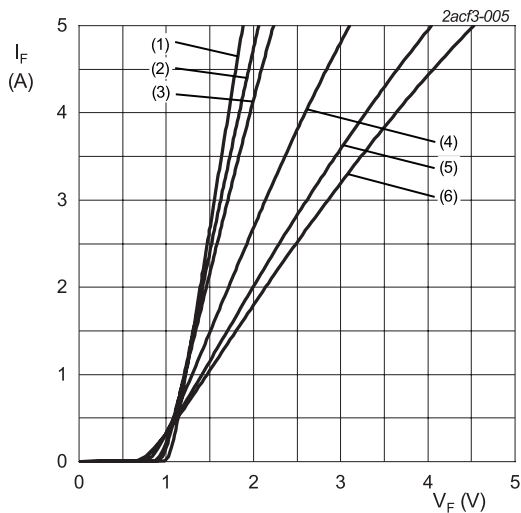


Fig. 4. Transient thermal impedance from junction to mounting base as a function of pulse duration

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Static characteristics							
V_F	forward current	$I_F = 2 \text{ A}; T_J = 25 \text{ }^\circ\text{C}; \text{ Fig. 5}$		-	1.45	1.65	V
		$I_F = 2 \text{ A}; T_J = 150 \text{ }^\circ\text{C}; \text{ Fig. 5}$		-	1.95	2.30	V
		$I_F = 2 \text{ A}; T_J = 175 \text{ }^\circ\text{C}; \text{ Fig. 5}$		-	2.10	2.60	V
I_R	reverse current	$V_R = 1200 \text{ V}; T_J = 25 \text{ }^\circ\text{C}; \text{ Fig. 6}$		-	0.5	10	μA
		$V_R = 1200 \text{ V}; T_J = 175 \text{ }^\circ\text{C}; \text{ Fig. 6}$		-	25	250	μA
Dynamic characteristics							
Q_r	recovered charge	$I_F = 2 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 500 \text{ A}/\mu\text{s}; T_J = 25 \text{ }^\circ\text{C}; \text{ Fig. 7}$		-	8	-	nC
C_d	diode capacitance	$f = 1 \text{ MHz}; V_R = 1 \text{ V}; T_J = 25 \text{ }^\circ\text{C}$		-	95	-	pF
		$f = 1 \text{ MHz}; V_R = 400 \text{ V}; T_J = 25 \text{ }^\circ\text{C}$		-	10	-	pF
		$f = 1 \text{ MHz}; V_R = 800 \text{ V}; T_J = 25 \text{ }^\circ\text{C}$		-	8	-	pF
E_{as}	non-repetitive avalanche energy	$I_R = 2.4 \text{ A}; L = 10 \text{ mH}; T_{j(\text{init})} = 25 \text{ }^\circ\text{C}$		28.8	-	-	mJ



$V_o = 0.889 \text{ V}; R_s = 0.6724 \text{ } \Omega$
 (1) $T_J = -55 \text{ }^\circ\text{C};$ typical values
 (2) $T_J = 0 \text{ }^\circ\text{C};$ typical values
 (3) $T_J = 25 \text{ }^\circ\text{C};$ typical values
 (4) $T_J = 100 \text{ }^\circ\text{C};$ typical values
 (5) $T_J = 150 \text{ }^\circ\text{C};$ typical values
 (6) $T_J = 175 \text{ }^\circ\text{C};$ typical values

Fig. 5. Forward current as a function of forward voltage; typical values

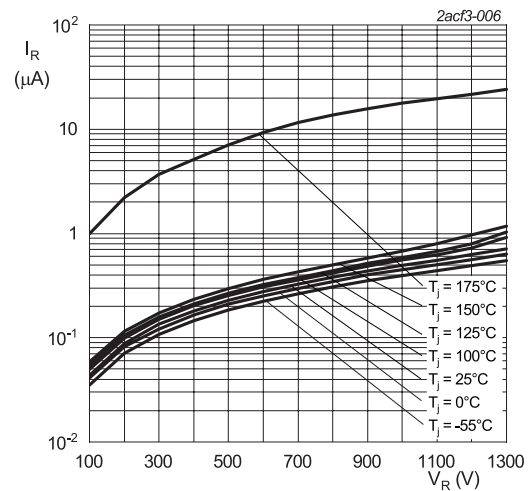


Fig. 6. Reverse leakage current as a function of reverse voltage; typical value

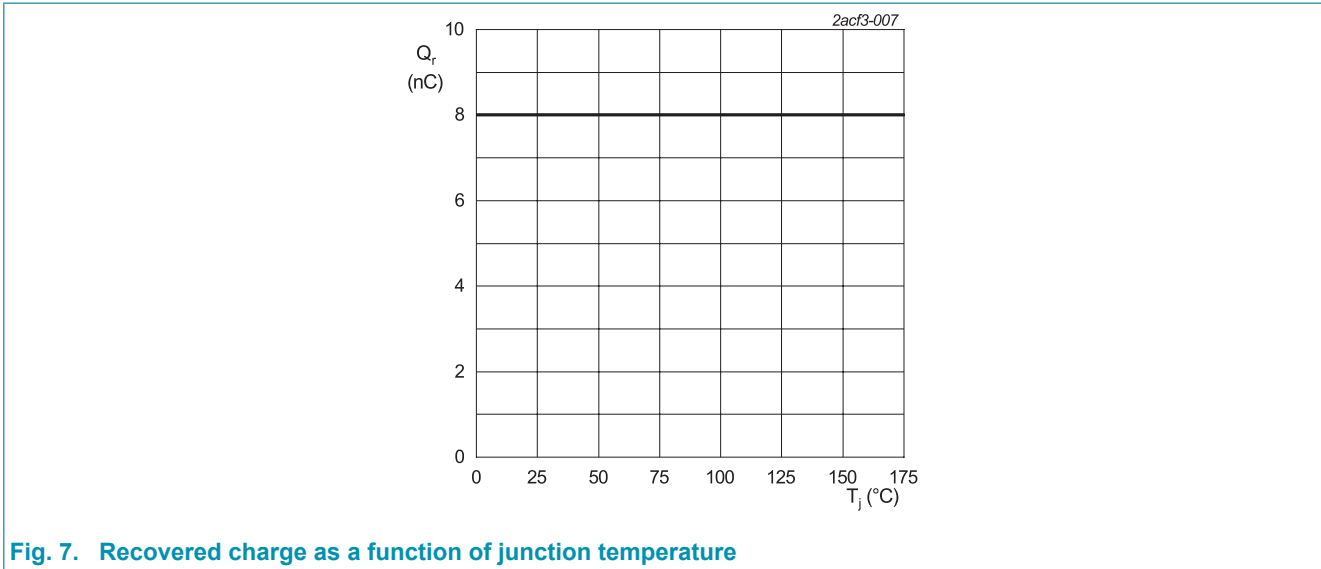
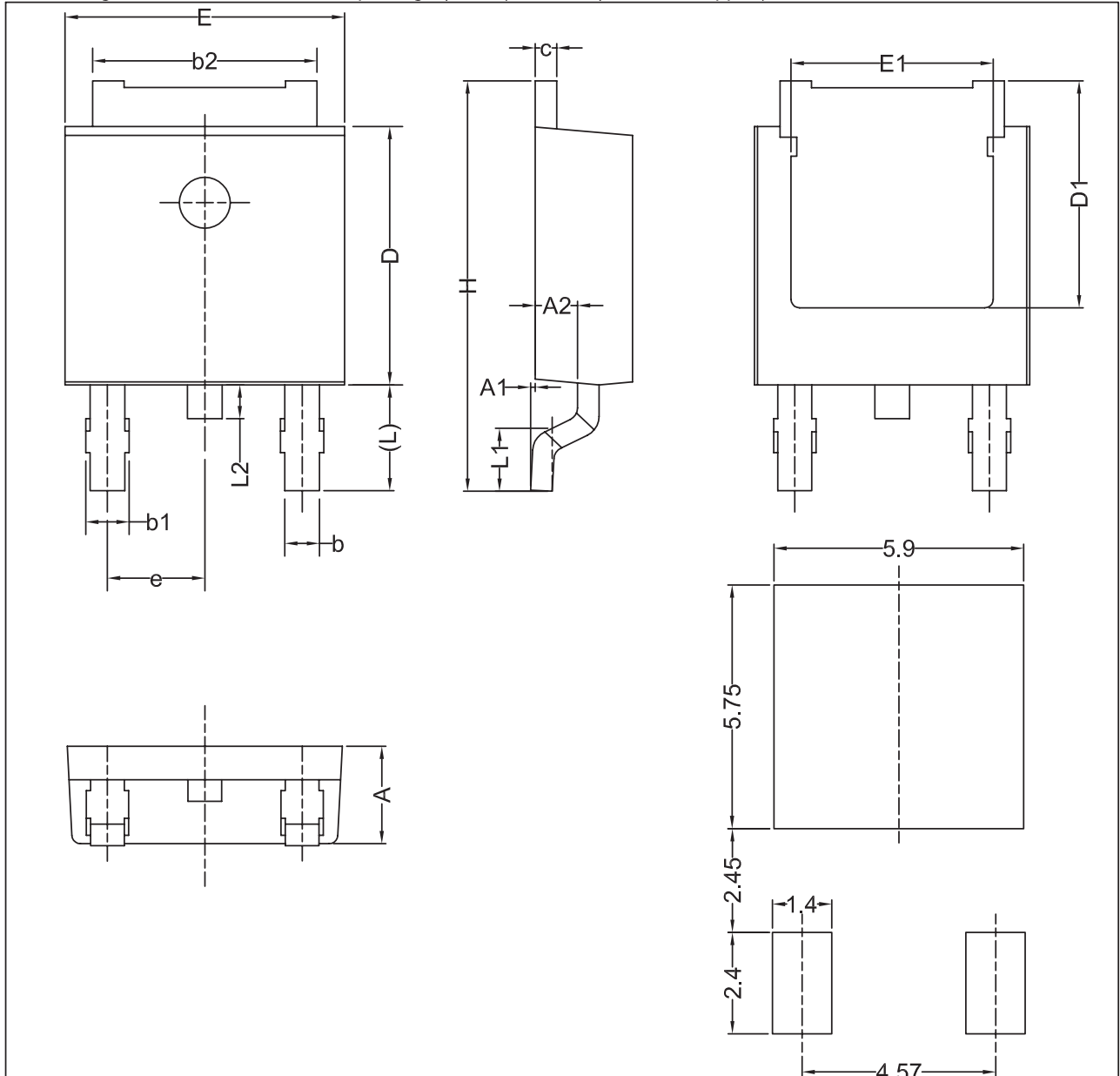


Fig. 7. Recovered charge as a function of junction temperature

11. Package outline

Plastic single-ended surface-mounted package (DPAK); 3 leads (one lead cropped) TO252



Recommended Footprint

	A	A1	A2	b	b1	b2	c	D	D1	e	E	E1	H	L	L1	L2
min	2.20	0	0.90	0.71	0.72	5.23	0.47	5.98	5.25	2.285	6.47	4.70	9.60	2.90	1.40	0.50
max	2.38	0.10	1.10	0.89	1.10	5.43	0.60	6.22	---	(typ)	6.73	---	10.40	(Ref.)	1.70	1.00

12. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions".
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